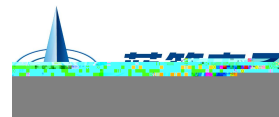


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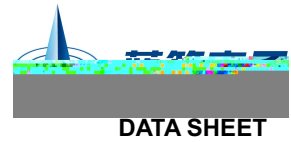


DATA SHEET

版本	修订日期	有修订的页码	修订涉及的内容	拟制	审核
A	202				

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PDFN5×6 N
N-Channel MOSFET in a PDFN5×6 Plastic Package .

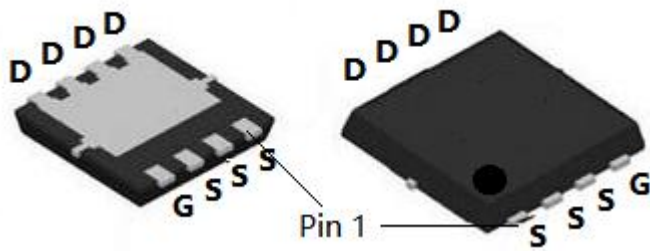
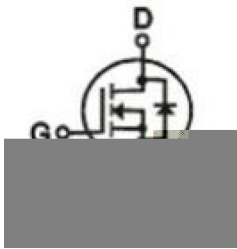
Low $R_{DS(ON)}$ to minimize conductive loss;low Gate Charge for fast switching;Low Thermal resistance;HF Product.

MB/NB/UMPC/VGA

Buck

-

Battery Management,High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA,Networking DC-DC Power System,Load Switch.

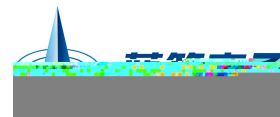


PIN1、 2、 3: S PIN4: G PIN5、 6、 7、 8: D

See Marking Instructions.

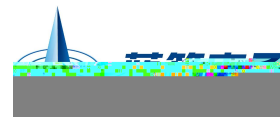
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DATA SHEET

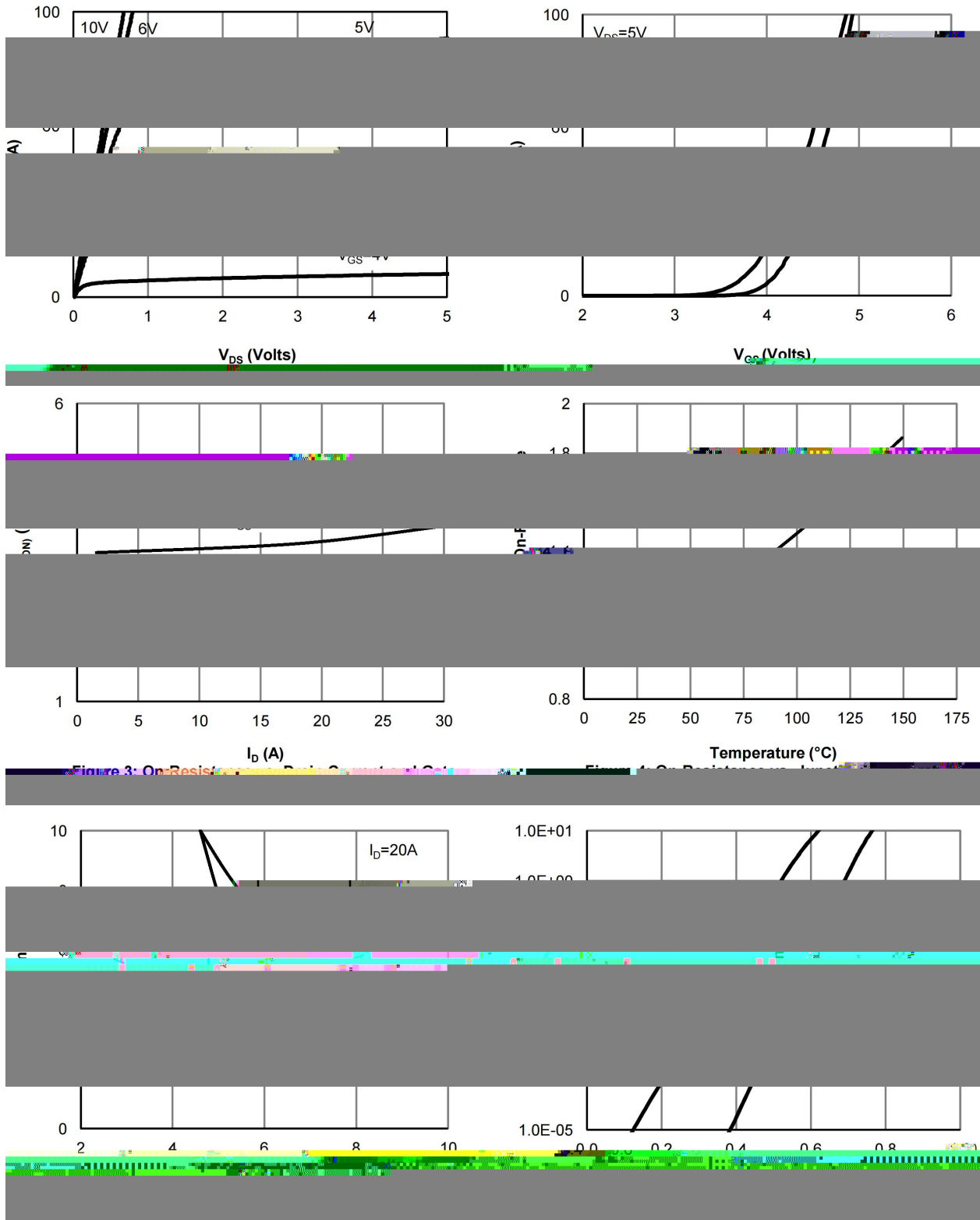
Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	100	V
Drain Current - Continuous	I_D	168	A
Drain Current – Pulsed	I_{DM}	400	A
Gate-Source Voltage	V_{GS}	± 20	V
Power Dissipation	$P_D(T_c=25^\circ\text{C})$	215	W
Single Pulse Avalanche Energy(L=0.5mH)	E_{AS}	563	mJ
Avalanche Current(L=0.5mH)	I_{AS}	37.5	A
Junction and Storage Temperature Range	T_j, T_{stg}	-55 to 150	$^\circ\text{C}$
Thermal resistance, junction - ambient $t \leq 10\text{s}$	$R_{\theta JA}$		



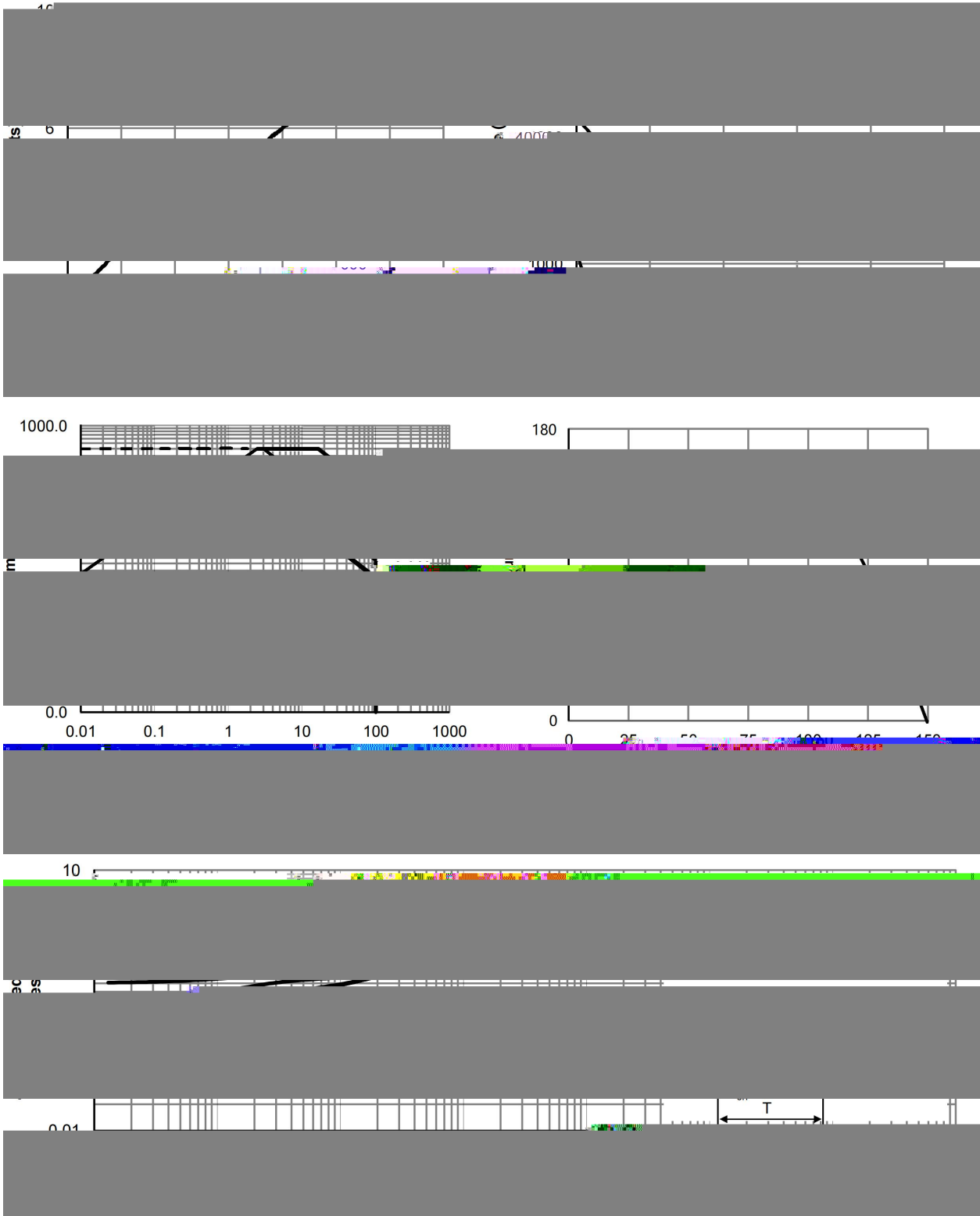
/ Electrical Characteristics(Ta=25)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Turn-On Delay Time	$t_{d(on)}$	$V_{GS}=10V$ $V_{DS}=50V$ $R_L=2.5\ \Omega$ $R_{GEN}=3\ \Omega$		19		ns
Turn-On Rise Time	t_r			8		
Turn-Off Delay Time	$t_{d(off)}$			32		
Turn-Off Fall Time	t_f			11		

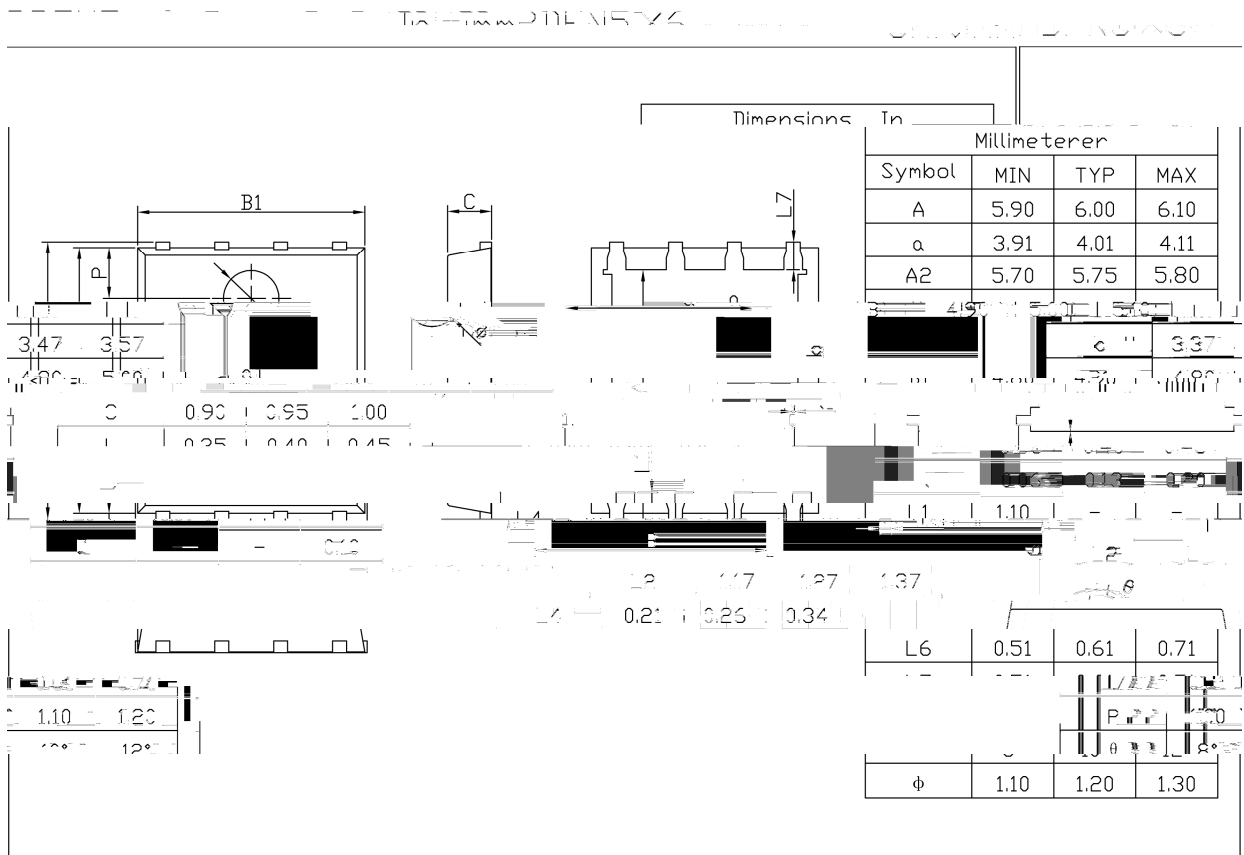
/ Electrical Characteristic Curve



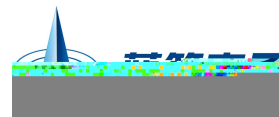
/ Electrical Characteristic Curve



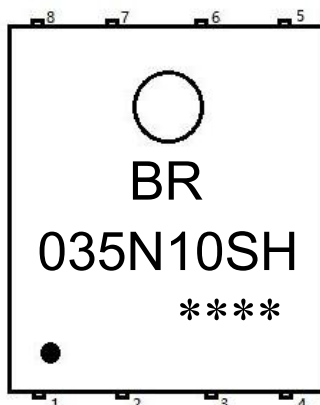
/ Package Dimensions



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/ Marking Instructions



BR

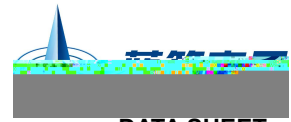
035N10SH

Note

BR Company Code

035N10SH Product Type

****: Lot No. Code, code change with Lot No



() / Temperature Profile for IR Reflow Soldering(Pb-Free)

Note:

- | | | | |
|---|---------|-----------|--|
| 1 | 150 180 | 60 90sec; | 1.Preheating:150~180°C, Time:60~90sec. |
| 2 | 245±5 | 5±0.5sec; | 2.Peak Temp.:245±5°C, Duration:5±0.5sec. |
| 3 | 2 | 10°C/sec. | 3. Cooling Speed: 2~10°C/sec. |

/ Resistance to Soldering Heat Test Conditions

260±5°C	10±1 sec.	Temp.:260±5°C	Time:10±1 sec
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/ Packaging SPEC.